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# 2SB1001

Silicon PNP Epitaxial

# HITACHI

ADE-208-1034 (Z)

1st. Edition

Mar. 2001

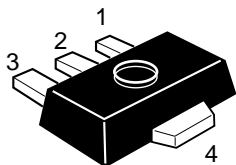
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## Application

- Low frequency power amplifier
- Complementary pair with 2SD1367

## Outline

UPAK



1. Base
2. Collector
3. Emitter
4. Collector (Flange)

## Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	-20	V
Collector to emitter voltage	$V_{CEO}$	-16	V
Emitter to base voltage	$V_{EBO}$	-6	V
Collector current	$I_C$	-2	A
Collector peak current	$i_{C(peak)}^{*1}$	-3	A
Collector power dissipation	$P_C^{*2}$	1	W
Junction temperature	$T_j$	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1.  $PW \leq 10$  ms, Duty cycle  $\leq 20\%$

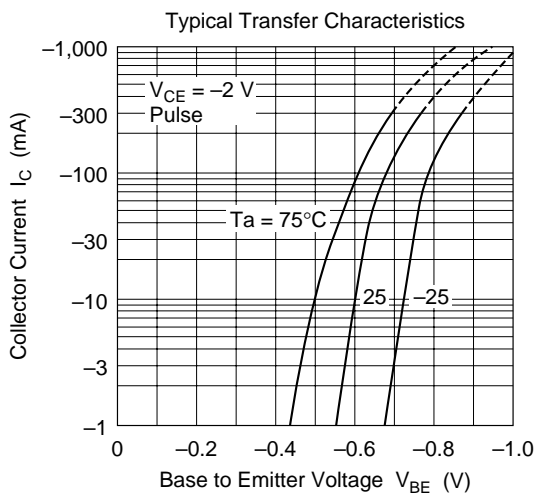
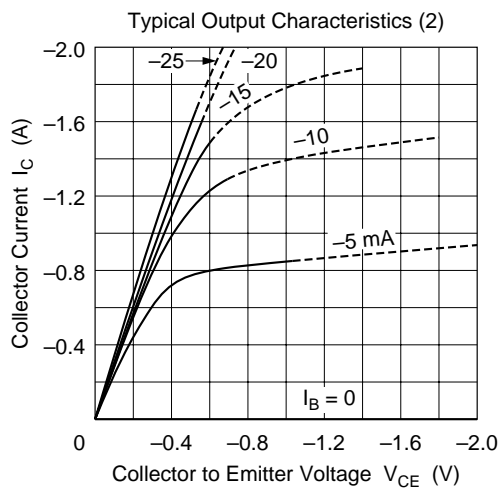
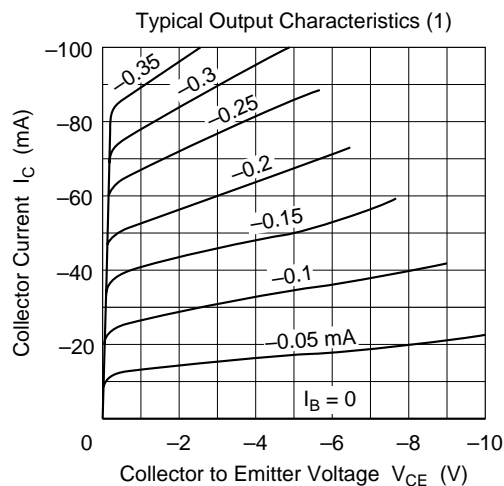
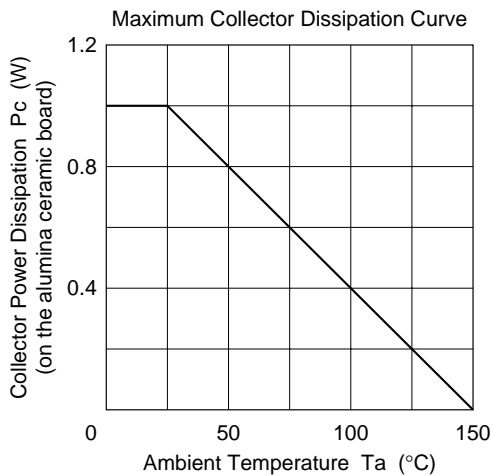
2. Value on the alumina ceramic board ( $12.5 \times 20 \times 0.7$  mm)

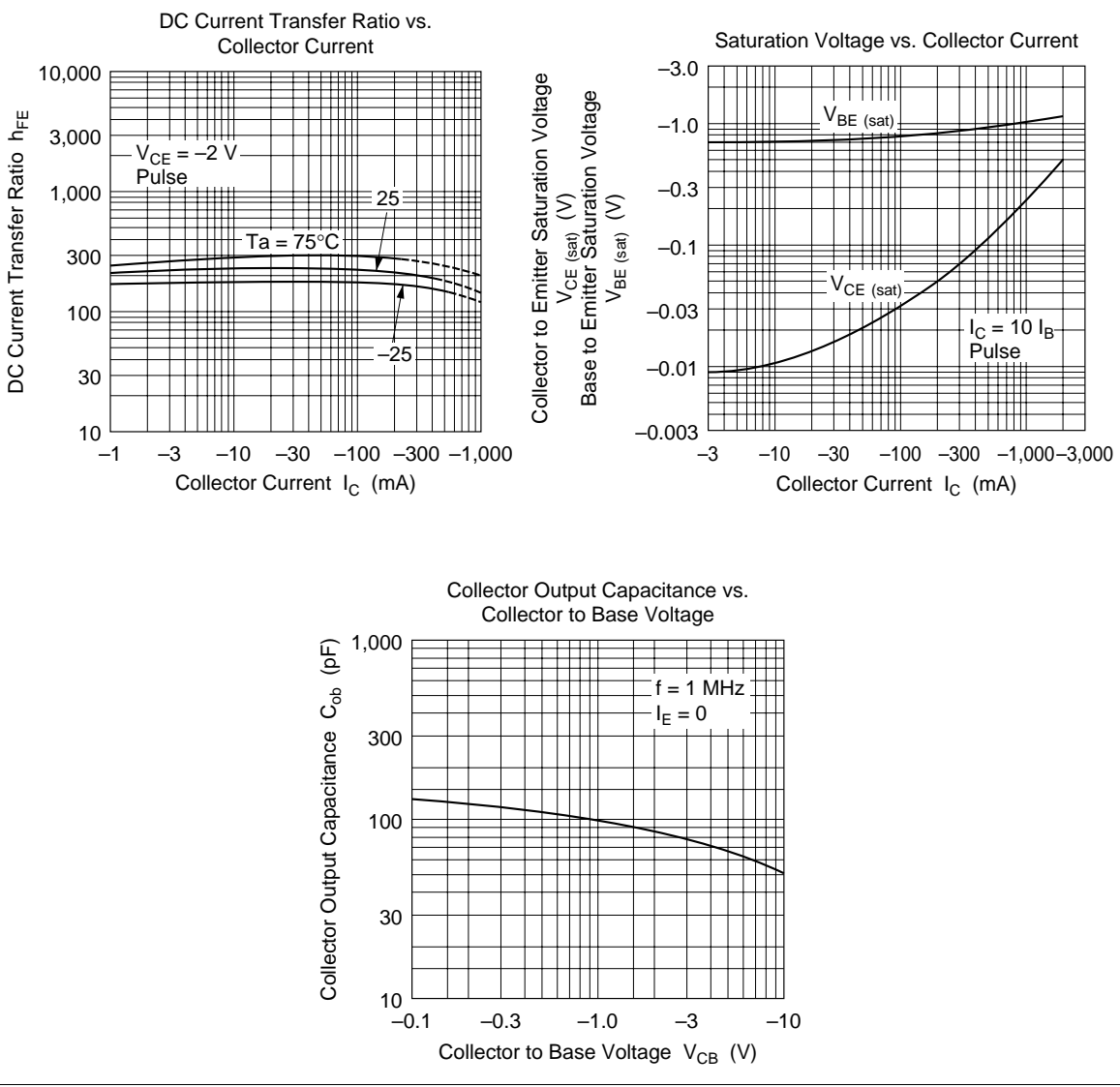
## Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-20	—	—	V	$I_C = -10 \mu A$ , $I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-16	—	—	V	$I_C = -1$ mA, $R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-6	—	—	V	$I_E = -10 \mu A$ , $I_C = 0$
Collector cutoff current	$I_{CBO}$	—	—	-0.1	$\mu A$	$V_{CB} = -16$ V, $I_E = 0$
Emitter cutoff current	$I_{EBO}$	—	—	-0.1	$\mu A$	$V_{EB} = -5$ V, $I_C = 0$
DC current transfer ratio	$h_{FE}^{*1}$	100	—	320		$V_{CE} = -2$ V, $I_C = -0.1$ A (Pulse test)
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	-0.15	-0.3	V	$I_C = -1$ A, $I_B = -0.1$ A (Pulse test)
Base to emitter saturation voltage	$V_{BE(sat)}$	—	-1.0	-1.2	V	$I_C = -1$ A, $I_B = -0.1$ A (Pulse test)
Gain bandwidth product	$f_T$	—	150	—	MHz	$V_{CE} = -2$ V, $I_C = -10$ mA
Collector output capacitance	Cob	—	50	—	pF	$V_{CB} = -10$ V, $I_E = 0$ , $f = 1$ MHz

Note: 1. The 2SB1001 is grouped by  $h_{FE}$  as follows.

Mark	BH	BJ
$h_{FE}$	100 to 200	160 to 320

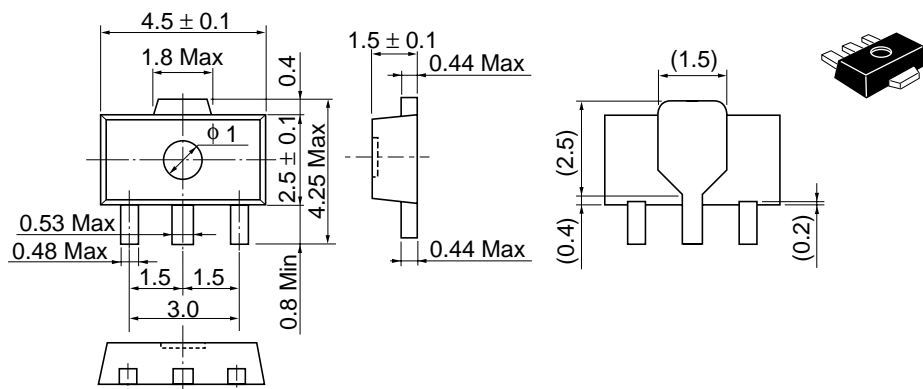




## Package Dimensions

As of January, 2001

Unit: mm



Hitachi Code	UPAK
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.050 g

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